

INFLUENCE OF ELECTRON IRRADIATION ON MOS STRUCTURE WITH CZ AND NCZ SILICON SUBSTRATE

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Received 30 April 2011; accepted 15 May 2011.

1. Introduction

Research is oriented on some properties of the MOS structure with grown silicon substrate by a standard Czochralski method (CZ) as well as with a substrate prepared by Czochralski-grown nitrogen-doped (NCZ) silicon irradiated with electrons using different fluences. The electro-physical parameters as a flatband voltage, effective charge density of MOS structure were calculated and analysed from extracted data of the C-V plots. Nitrogen doping attracts much attention because of some benefits against to CZ silicon. In addition to increasing the mechanical strength and strong dislocation locking, nitrogen, even in low concentration, enhances the nucleation and allows controlling oxide precipitation [1,2]. The aim of this work is to investigate and analyse the influence of electron irradiation on the parameters of the NCZ structure with respect to its above mentioned structural properties and compare such as obtained results with those measured on the CZ structure.

2. Experimental

The P-type (boron-doped) silicon substrates were grown by the method of Czochralski. A number of Si wafers coated on both sides by 1 μm LP CVD-grown Si_3N_4 were used as a source of nitrogen by adding into the melt. The nitrogen-doped wafers and the reference CZ samples with the same resistivity ranges from 2 to 5 Ωcm and thickness of 500 μm were used in the experiment. SiO_2 gate layer was prepared by thermal oxidation in

O₂+H₂O ambient at 1050°C resulting in the oxide thickness of 100 nm. Nitrogen concentration for NCZ was $1.6 \times 10^{15} \text{ cm}^{-3}$. Aluminium gates were vapour deposited and patterned photolithographically. After manufacturing the MOS structures, the samples were annealed in the forming gas at 460°C for 20 minutes. The C-V measurements were carried out with the C-V measurement set up [1]. The electron irradiation by the linear accelerator 5MeV/1kW was performed at the Slovak Medical University, Trenčín. The structures were exposed to electron irradiation with the fluences of $1.4 \times 10^{15} \text{ cm}^{-2}$, $5 \times 10^{15} \text{ cm}^{-2}$, $1.7 \times 10^{16} \text{ cm}^{-2}$ and $5.3 \times 10^{16} \text{ cm}^{-2}$.

3. Results and discussion

The experimental data obtained from C-V and C-t measurements are summarized in Table 1. The radiation-induced changes of the C-V plots for the CZ and NCZ structures are shown in Fig.1 and Fig.2 for both, the $1.0 \times 10^{15} \text{ cm}^{-2}$ and $5.0 \times 10^{15} \text{ cm}^{-2}$ fluences, respectively.

Tab. 1: *Summary of experimental data.*

Fluence of electrons	Substrate N-type	U_{FB} [V]	N_{ef} [m^{-2}]	S_g [ms^{-1}]	τ_g [μs]
nonirradiated	CZ48	-0,8	1.24×10^{15}	9.3×10^{-4}	262.5
	NCZ37	-0,8	1.33×10^{15}	6.5×10^{-4}	48.2
$1 \times 10^{15} \text{ cm}^{-2}$	CZ48	-4.55	1.20×10^{15}		
	NCZ37	-4.40	1.20×10^{15}		
$5 \times 10^{15} \text{ cm}^{-2}$	CZ48	-5.20	1.33×10^{15}		
	NCZ37	-5.05	1.40×10^{15}		

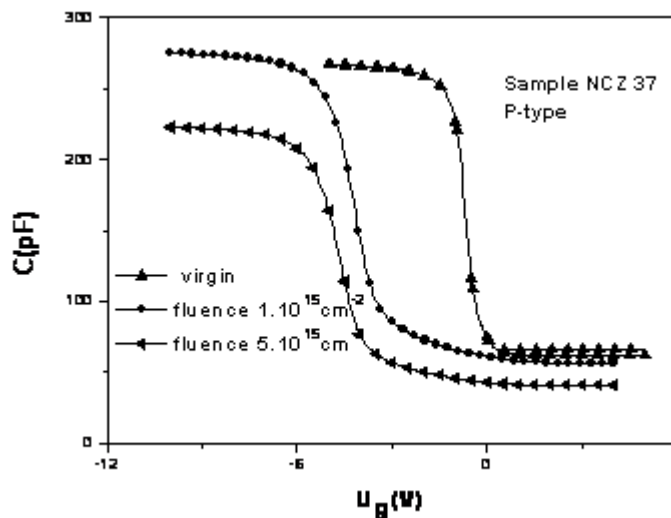


Fig.1: *The C-V characteristics of sample NCZ 37 before and after electron irradiation.*

The electron irradiation results in the shift to the negative voltage against virgin curve (Fig.1). This is typical distortion in a depletion region which indicates the presence of the voltage dependent charges in the Si-SiO₂ interface. The distortion C-V curves is observed in accumulation and inversion, as well.

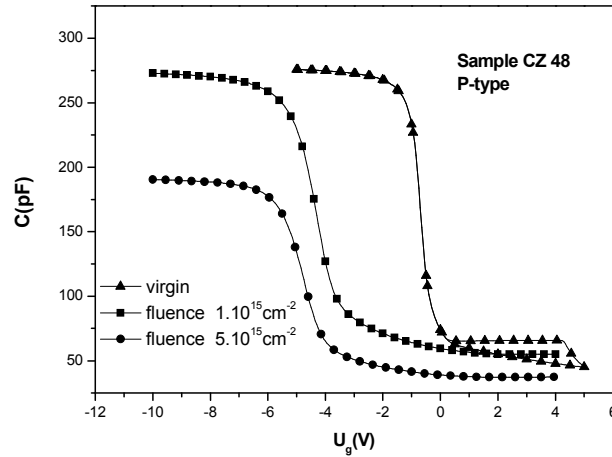


Fig.2: The C-V characteristics of sample CZ 48 before and after electron irradiation with different fluences.

The higher fluence has the same influence on a shift of the C-V curve for both, the CZ and NCZ structure but the higher fluence causes bigger influence on the C_{ox}/C_{min} ratio of the respective C-V chart.

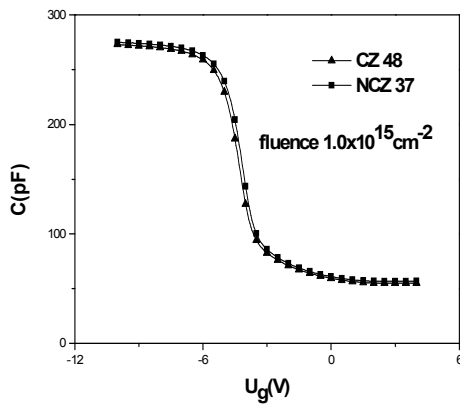


Fig. 3: Effect of $1.0 \times 10^{15} \text{ cm}^{-2}$ fluence on C-V plot of CZ and NCZ samples.

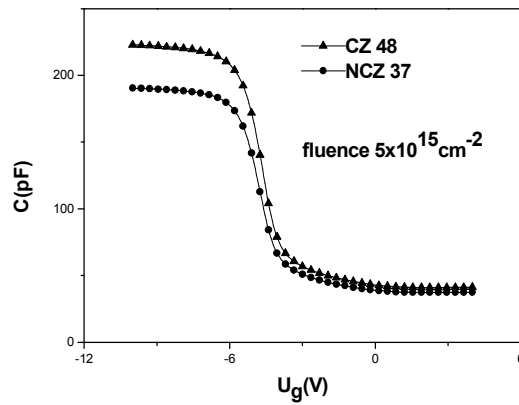


Fig. 4: Effect of $5 \times 10^{15} \text{ cm}^{-2}$ fluence on C-V plot of CZ and NCZ samples

The electron fluences higher than $5.0 \times 10^{15} \text{ cm}^{-2}$ resulted in degradation of C-V plot. Therefore, the evaluation of results such as samples was impossible.

4. Conclusion

The effect of electron irradiation, using $1.0 \times 10^{15} \text{cm}^{-2}$, $5.0 \times 10^{15} \text{cm}^{-2}$, $1.7 \times 10^{16} \text{cm}^{-2}$ and $5.3 \times 10^{16} \text{cm}^{-2}$ fluences on the MOS structure with CZ and NCZ type of substrates was investigated. The higher electron fluence the bigger negative voltage shift was detected as in before a very similar performed experiments [3]. No relevant differences were observed on C-V plot for both the CZ and NCZ samples irradiated with $1.0 \times 10^{15} \text{cm}^{-2}$ and $5.0 \times 10^{15} \text{cm}^{-2}$ electron fluences. The fluences $1.7 \times 10^{16} \text{cm}^{-2}$ and $5.3 \times 10^{16} \text{cm}^{-2}$ resulted in total degradation of C-V plot.

Acknowledgement

Authors would like to thank to dr.M. Fülöp from the UV VPLU SMU, Trenčín for his help at the samples irradiation.

This work was partially supported by the Slovak Grant Agency, Project # VEGA 1/0507/09 and # KEGA project 3/7413/09, as well.

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